

## INFORMATION DISCLOSURE CITATION

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Applicants	Takashi YODA et al.		
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U.S. PATENT DOCUMENTS							
Examiner Initial*		Document Number	Issue Date	Name	Class	Sub Class	Filing Date If Appropriate
PC		2003-0116854-A1	06/26/03	ITO et al.	257	761	

FOREIGN PATENT DOCUMENTS							
		Document Number	Publication Date	Country	Class	Sub Class	Translation Yes or No
PC		2002-110789	04/12/02	JAPAN			ABSTRACT
PC		2002-176054	06/21/02	JAPAN			ABSTRACT

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)	
PC	LIN, J. C. et al., "CVD Barriers for Cu with Nanoporous Ultra Low-k: Integration and Reliability", International Interconnect Technology Conference, pp. 21-23, (2002).
PC	MOSIG, K. et al., "Integration of Porous Ultra Low-k Dielectric with CVD Barriers", International Electron Device Meeting, pp. 88-91, (2001).

Examiner	PHAT X. GAO	Date Considered	1/5/05
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